

RoHS

COMPLIANT

### N-Channel 100-V (D-S) MOSFET

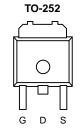
| PRODUCT SUMMARY     |                                   |                    |  |  |  |
|---------------------|-----------------------------------|--------------------|--|--|--|
| V <sub>DS</sub> (V) | R <sub>DS(on)</sub> (Ω)           | I <sub>D</sub> (A) |  |  |  |
| 100                 | 0.0075 at V <sub>GS</sub> = 10 V  | 85                 |  |  |  |
|                     | 0.0095 at V <sub>GS</sub> = 4.5 V | 75                 |  |  |  |

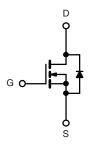
#### **FEATURES**

- TrenchFET<sup>®</sup> Power MOSFET
- 100 % R<sub>g</sub> Tested
- 100 % UIS Tested

#### **APPLICATIONS**

- Primary Side Switch
- Isolated DC/DC Converter





N-Channel MOSFET

| <b>ABSOLUTE MAXIMUM RATINGS</b> $T_A = 25 \text{ °C}$ , unless otherwise noted |  |                 |                 |      |  |  |  |
|--|--|-----------------|-----------------|------|--|--|--|
| Parameter  |  |                 | Limit           | Unit |  |  |  |
| Drain-Source Voltage   |  |                 | 100             | v    |  |  |  |
| Gate-Source Voltage  |  |                 | ± 20            | v    |  |  |  |
| Continuous Drain Current (T <sub>J</sub> = 150 °C)                             | T <sub>C</sub> = 25 °C                             | 1.5             | 85              |      |  |  |  |
|  | T <sub>C</sub> = 125 °C                            | I <sub>D</sub>  | 75 <sup>a</sup> |      |  |  |  |
| Pulsed Drain Current   |  |                 | 300             | A    |  |  |  |
| Avalanche Current  | L = 0.1 mH   | I <sub>AS</sub> | 75              |      |  |  |  |
| Single Pulse Avalanche Energy <sup>b</sup>                                     |  | E <sub>AS</sub> | 280             | mJ   |  |  |  |
| Maximum Power Dissipation <sup>b</sup>   | $T_{C} = 25 \ ^{\circ}C \ (TO-252 \ and \ TO-251)$ | PD              | 210             | W    |  |  |  |
|  | T <sub>A</sub> = 25 °C (TO-252)                    | - 'D            | 3.25            | vv   |  |  |  |
| Operating Junction and Storage Temperat  | T <sub>J</sub> , T <sub>stg</sub>                  | - 55 to 175     | °C              |      |  |  |  |

| THERMAL RESISTANCE RATINGS               |              |                   |         |         |      |  |
|--|--------------|-------------------|---------|---------|------|--|
| Parameter                                |              | Symbol            | Typical | Maximum | Unit |  |
| Maximum Junction-to-Ambient <sup>b</sup> | Steady State | R <sub>thJA</sub> | 40      | 50      | °C/W |  |
| Maximum Junction-to-Case                 | Sleady Slale | R <sub>thJC</sub> | 0.85    | 1.1     | 0/10 |  |

Notes:

a. Package limited.

b. Surface mounted on 1" x 1" FR4 board.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



| Parameter                                     | Symbol                      | Test Conditions  | Min.                       | Тур.     | Max.     | Unit  |  |
|---|-----------------------------|--|----------------------------|----------|----------|-------|--|
| Static  |                             | ·  |                            |          |          |       |  |
| Drain-Source Breakdown Voltage                | V <sub>DS</sub>             | $V_{GS} = 0 V, I_D = 250 \mu A$  |                            |          |          | V     |  |
| Gate-Threshold Voltage                        | V <sub>GS(th)</sub>         | $V_{DS} = V_{GS}, I_{D} = 250 \ \mu A$   |                            |          | 3        | V     |  |
| Gate-Body Leakage                             | I <sub>GSS</sub>            | $V_{DS} = 0 V, V_{GS} = \pm 20 V$  |                            |          | ± 100    | nA    |  |
|   |                             | $V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}$   |                            |          | 1        |       |  |
| Zero Gate Voltage Drain Current               | I <sub>DSS</sub>            | $V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$                 |                            |          | 50       | μA    |  |
|   |                             | $V_{DS} = 100 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 175 ^{\circ}\text{C}$ | T <sub>J</sub> = 175 °C 25 |          | 250      | -     |  |
| On-State Drain Current <sup>a</sup>           | I <sub>D(on)</sub>          | $V_{DS} = \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$  | 120                        |          |          | А     |  |
|   |                             | $V_{GS} = 10 \text{ V}, \text{ I}_{D} = 30 \text{ A}$  | = 30 A                     |          |          | <br>I |  |
|   | R                           | $V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 20 \text{ A}$                                       |                            | 0.0095   |          | Ω     |  |
| Drain-Source On-State Resistance <sup>a</sup> | R <sub>DS(on)</sub>         | $V_{GS} = 10 \text{ V}, \text{ I}_{D} = 30 \text{ A}, \text{ T}_{J} = 125 ^{\circ}\text{C}$  |                            | 0.017    |          |       |  |
|   |                             | $V_{GS} = 10 \text{ V}, \text{ I}_{D} = 30 \text{ A}, \text{ T}_{J} = 175 ^{\circ}\text{C}$  |                            | 0.022    |          |       |  |
| Forward Transconductance <sup>a</sup>         | 9 <sub>fs</sub>             | V <sub>DS</sub> = 15 V, I <sub>D</sub> = 30 A  | 25                         |          |          | S     |  |
| Dynamic <sup>b</sup>                          |                             | •  |                            | <b>I</b> | <u> </u> |       |  |
| Input Capacitance                             | C <sub>iss</sub>            |  |                            | 4550     |          | pF    |  |
| Output Capacitance                            | C <sub>oss</sub>            | V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1 MHz                                     |                            | 565      |          |       |  |
| Reverse Transfer Capacitance                  | C <sub>rss</sub>            |  |                            | 205      |          |       |  |
| Total Gate Charge <sup>c</sup>                | Qg                          |  |                            | 105      | 160      | nC    |  |
| Gate-Source Charge <sup>c</sup>               | Q <sub>gs</sub>             | $V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 85 \text{ A}$                         |                            | 17       |          |       |  |
| Gate-Drain Charge <sup>c</sup>                | Q <sub>gd</sub>             |  |                            | 23       |          |       |  |
| Turn-On Delay Time <sup>c</sup>               | t <sub>d(on)</sub>          |  |                            | 12       | 25       |       |  |
| Rise Time <sup>c</sup>                        | t <sub>r</sub>              | $V_{DD} = 50 \text{ V}, \text{ R}_{L} = 0.6 \Omega$  |                            | 90       | 135      |       |  |
| Turn-Off DelayTime <sup>c</sup>               | t <sub>d(off)</sub>         | $I_D \cong 85 \text{ A}, V_{GEN} = 10 \text{ V}, \text{ R}_g = 2.5 \Omega$                   |                            | 55       | 85       | ns    |  |
| Fall Time <sup>c</sup>                        | t <sub>f</sub>              |  |                            | 130      | 195      |       |  |
| Source-Drain Diode Ratings and Cha            | racteristics T <sub>C</sub> | = 25 °C <sup>b</sup>   |                            |          |          |       |  |
| Continuous Current                            | I <sub>S</sub>              | <u> </u>   |                            |          | 85       |       |  |
| Pulsed Current                                | I <sub>SM</sub>             |  |                            |          | 240      | A     |  |
| Forward Voltage <sup>a</sup>                  | V <sub>SD</sub>             | I <sub>F</sub> = 85 A, V <sub>GS</sub> = 0 V   |                            | 1.0      | 1.5      | V     |  |
| Reverse Recovery Time                         | t <sub>rr</sub>             |  |                            | 85       | 140      | ns    |  |
| Peak Reverse Recovery Current                 | I <sub>RM(REC)</sub>        | I <sub>F</sub> = 50 A, dl/dt = 100 A/μs  |                            | 4.5      | 7        | А     |  |
| Reverse Recovery Charge                       | Q <sub>rr</sub>             | 1  |                            | 0.17     | 0.35     | μC    |  |

Notes:

a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

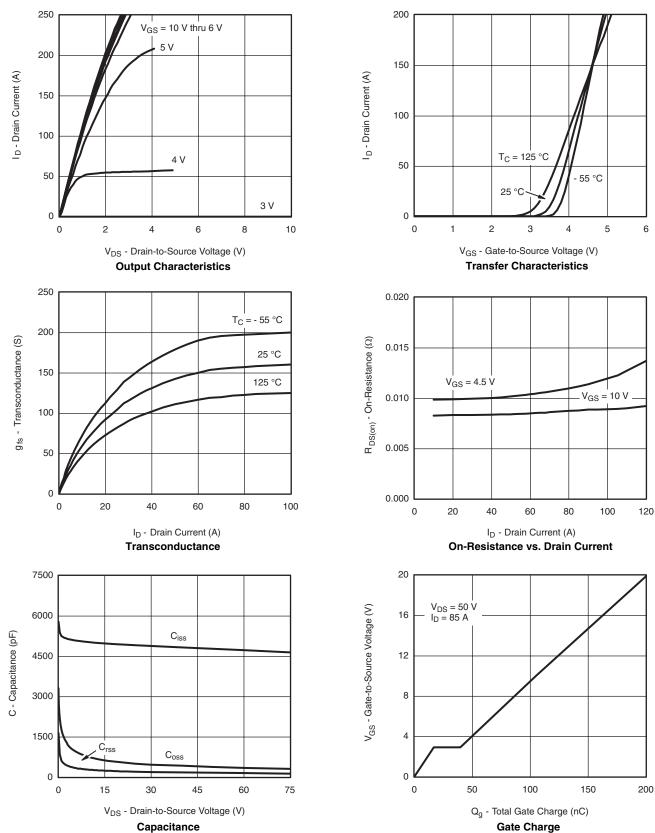
b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

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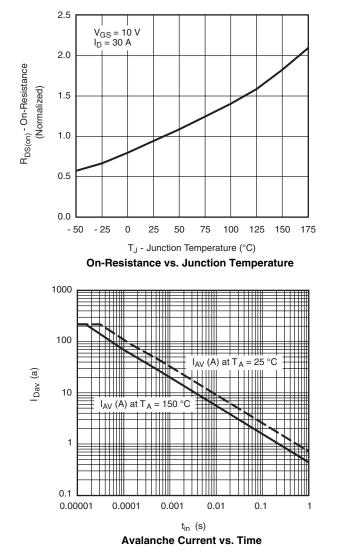


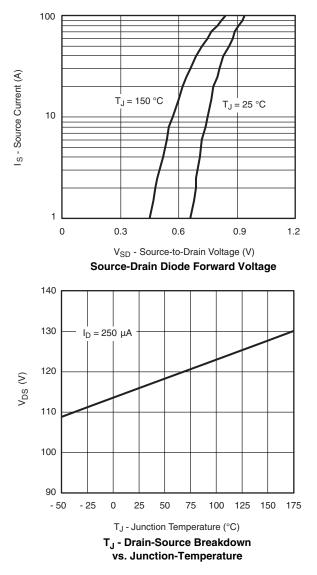
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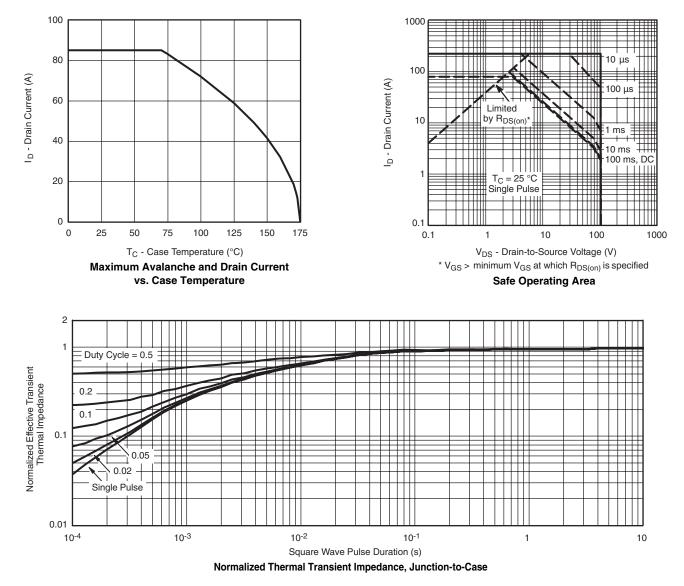
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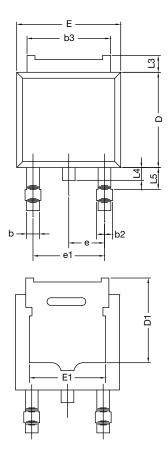


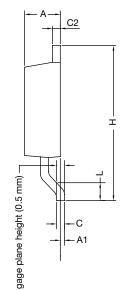
#### **THERMAL RATINGS**





# **TO-252AA CASE OUTLINE**





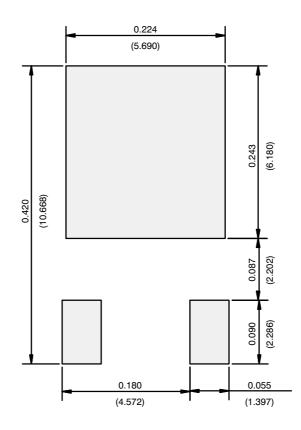
|  | MILLIMETERS |          | INCHES    |       |  |
|--|-------------|----------|-----------|-------|--|
| DIM.   | MIN.        | MAX.     | MIN.      | MAX.  |  |
| А  | 2.18        | 2.38     | 0.086     | 0.094 |  |
| A1   | -           | 0.127    | -         | 0.005 |  |
| b  | 0.64        | 0.88     | 0.025     | 0.035 |  |
| b2   | 0.76        | 1.14     | 0.030     | 0.045 |  |
| b3   | 4.95        | 5.46     | 0.195     | 0.215 |  |
| С  | 0.46        | 0.61     | 0.018     | 0.024 |  |
| C2   | 0.46        | 0.89     | 0.018     | 0.035 |  |
| D  | 5.97        | 6.22     | 0.235     | 0.245 |  |
| D1   | 5.21        | -        | 0.205     | -     |  |
| E  | 6.35        | 6.73     | 0.250     | 0.265 |  |
| E1   | 4.32        | -        | 0.170     | -     |  |
| Н  | 9.40        | 10.41    | 0.370     | 0.410 |  |
| е  | 2.28        | 2.28 BSC |           | BSC   |  |
| e1   | 4.56 BSC    |          | 0.180 BSC |       |  |
| L  | 1.40        | 1.78     | 0.055     | 0.070 |  |
| L3   | 0.89        | 1.27     | 0.035     | 0.050 |  |
| L4   | -           | 1.02     | -         | 0.040 |  |
| L5   | 1.14        | 1.52     | 0.045     | 0.060 |  |
| ECN: X12-0247-Rev. M, 24-Dec-12<br>DWG: 5347 |             |          |           |       |  |

Note

• Dimension L3 is for reference only.



### **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)



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